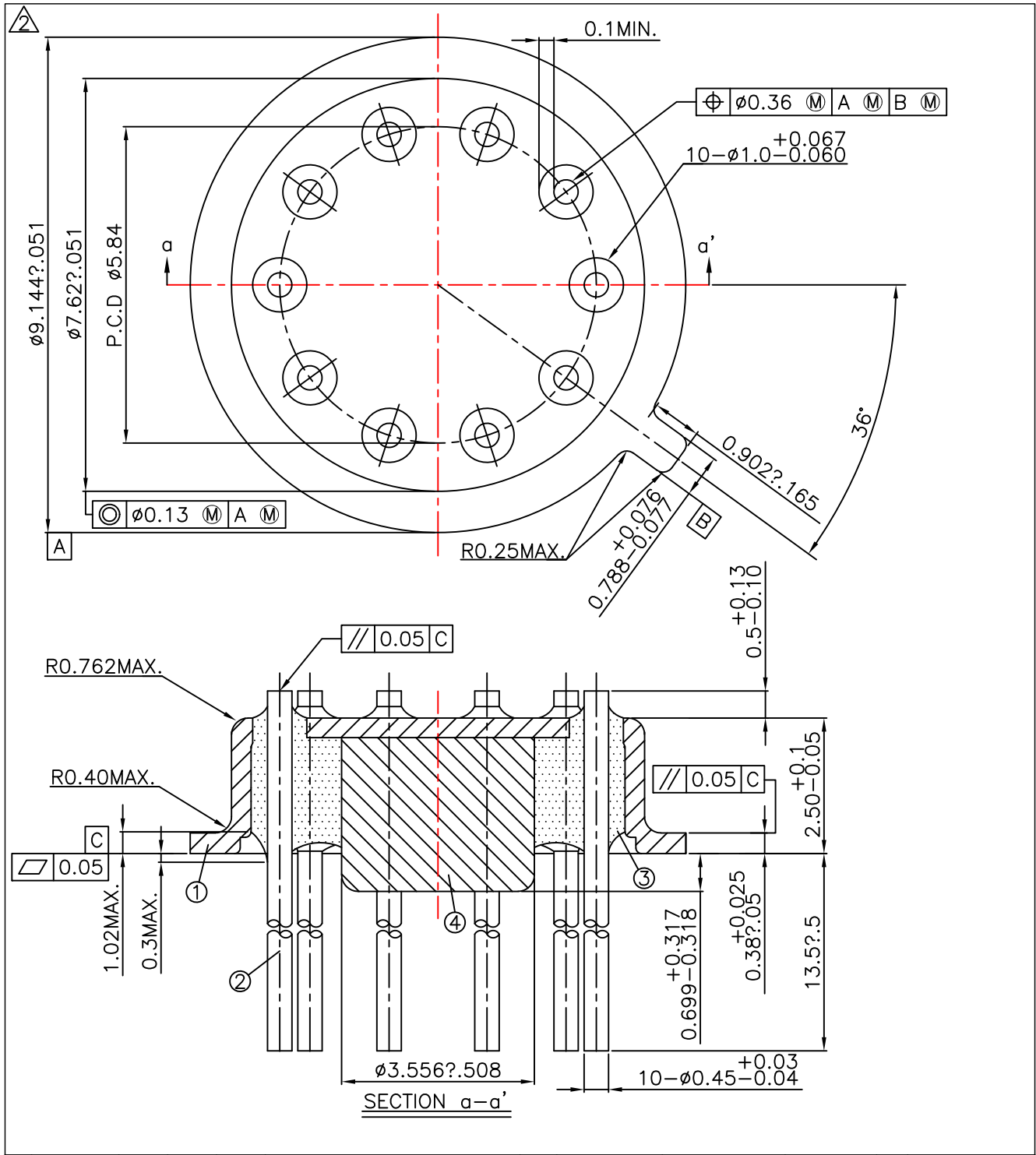


SSM P/N HDR00568



REV	DATE	DSGN	CHECK	APPR	DESCRIPTION	ITEM	DESCRIPTION	DWG NO.	MATERIAL	QTY
02	'20.12.22	CW.PARK	JY.JEONG	JY.JEONG	Change the outer lead shape(3)	1	EYELET		KOVAR	1
						2	LEAD		KOVAR	10
						3	GLASS		HARD GLASS	1
						4	STAND OFF		GLASS CERAMIC	1
NOTE: SPECTRUM SEMICONDUCTOR MATERIALS, INC.										
DATE DESIGNED DRAWN CHECKED APPR'D TITLE						TO-5/10PIN				
'20.11.25 CW.PARK CW.PARK HS.KIM T.MIYA						PROJ SCALE DRAWING NO.				
KOREA SHINKO MICROELECTRONICS CO.,LTD.						3RD ANGLE 10:1		KR5490 2/3		



Notes.

1. Finish

Full gold 1.27umMIN. over 2.54umMIN. electrolytic nickel under plating.

- 1) Plating thickness : controlled on top of the post.
- 2) Measuring method : X-ray fluorescence machine.

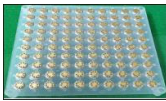
2. Packaging method.

2-1. Packaging material

	Transportation box	Tray	Vacuum bag	Air cap	Silicagel
Packing material	Carton box	CBX-148	Plastic pack	Air cap	Silicagel
Size	275X555X250	130X130X12	136X272X430	210X310X15	4g
Quantity(8,640pcs)	1	152	8	Suitable	Suitable

2-2. Packaging method

- 1) Put 100 pcs parts in 2 carrier.



- 2) The carrier containing the parts is piled 9 carrier, and empty carrier is put on the top.(total 19 carrier)
- 3) The carrier containing a parts of a 19 pile is put into Plastic bag with silica gel.



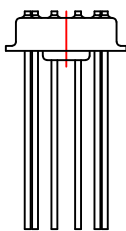
- 4) Operate 1) to 3) method 8 times repeatedly. (vacuumed Plastic bags – total of 8)
- 5) 8 Plastic bags are put Transportation box.



- 6) Tapping the outside box.



3. No coning



02	'20.12.22	CW.PARK	JY.JEONG	JY.JEONG	Change the outer lead shape(2)	MATERIAL	FINISH	NOTE
REV	DATE	DSGN	CHECK	APPR	DESCRIPTION			
	DATE	DESIGNED	DRAWN	CHECKED	APPR'D	TITLE		
	'20.11.25	CW.PARK	CW.PARK	HS.KIM	T.MIYA	TO-5/10PIN		
KOREA SHINKO MICROELECTRONICS CO.,LTD.						PROJ 3RD ANGLE	SCALE	DRAWING NO. KR5490 3/3

